



Product Change Notification

Change Notification #: 117086 - 00
Change Title: Select Intel® SSD DC P4510 Series and P4610 Series Products, PCN 117086-00, Product Material, DRAM Updates
Date of Publication: August 6, 2019

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	November 4, 2019
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Description of Change to the Customer:

The Intel® SSD DC P4510 Series and P4610 Series SKUs listed in the Products Affected table below will undergo the following DRAM updates:

Affected Product Codes	Changes
SSDPE2KX020T801 SSDPE2KX020T810 SSDPE2KX020T8OP SSDPE2KX020T8OS	Add alternate the Nanya 4Gbx4 DRAM to current BOM since the current 4Gbx4 Micron DRAM will be EOL Q3'2019

Affected Product Codes	Changes
SSDPE2KE016T801 SSDPE2KE016T8OP SSDPE2KE016T8OS	Add alternate the Nanya 4Gbx4 DRAM to current BOM since the current 4Gbx4 Micron DRAM will be EOL Q3'2019

Affected Product Codes	Changes
SSDPE2KX040T801 SSDPE2KX040T810 SSDPE2KX040T8OP SSDPE2KX040T8OS	Add alternate the Nanya 4Gbx4 DRAM to current BOM since the current 4Gbx4 Micron DRAM will be EOL Q3'2019 Add alternate the Hynix 16Gbx8 DRAM to BOM since the current 16Gbx8 Micron DRAM will be EOL Q4'2019.

Affected Product Codes	Changes
SSDPE2KE032T801 SSDPE2KE032T8OP SSDPE2KE032T8OS	Add alternate the Nanya 4Gbx4 DRAM to current BOM since the current 4Gbx4 Micron DRAM will be EOL Q3'2019 Add alternate the Hynix 16Gbx8 DRAM to BOM since the current 16Gbx8 Micron DRAM will be EOL Q4'2019.

Customer Impact of Change and Recommended Action:

Intel will attempt to deplete pre-conversion material before shipping post-conversion material but there is a possibility of Intel shipping mixed inventory. Therefore, customers will need to manage and migrate to the post-conversion material as soon as possible.

Milestone dates are estimates and subject to change based on business and operational conditions.

Products Affected / Intel Ordering Codes:

Marketing Name	Product Code	MM#
Intel® SSD DC P4510 Series (2.0TB, 2.5in PCIe 3.1 x4, 3D2, TLC) Generic Single Pack	SSDPE2KX020T801	959393
Intel® SSD DC P4510 Series (2.0TB, 2.5in PCIe 3.1 x4, 3D2, TLC) Generic 10 Pack	SSDPE2KX020T810	959394
Intel® SSD DC P4510 Series (4.0TB, 2.5in PCIe 3.1 x4, 3D2, TLC) Generic Single Pack	SSDPE2KX040T801	959395
Intel® SSD DC P4510 Series (4.0TB, 2.5in PCIe 3.1 x4, 3D2, TLC) Generic 10 Pack	SSDPE2KX040T810	959396
Intel® SSD DC P4610 Series (1.6TB, 2.5in PCIe 3.1 x4, 3D2, TLC) Generic Single Pack	SSDPE2KE016T801	978083
Intel® SSD DC P4610 Series (3.2TB, 2.5in PCIe 3.1 x4, 3D2, TLC) Generic Single Pack	SSDPE2KE032T801	978084
Intel® SSD DC P4510 Series (2.0TB, 2.5in PCIe 3.1 x4, 3D2, TLC) Generic Single Pack OPAL	SSDPE2KX020T8OS	984817
Intel® SSD DC P4510 Series (2.0TB, 2.5in PCIe 3.1 x4, 3D2, TLC) Generic 10 Pack OPAL	SSDPE2KX020T8OP	984818
Intel® SSD DC P4510 Series (4.0TB, 2.5in PCIe 3.1 x4, 3D2, TLC) Generic Single Pack OPAL	SSDPE2KX040T8OS	984819
Intel® SSD DC P4510 Series (4.0TB, 2.5in PCIe 3.1 x4, 3D2, TLC) Generic 10 Pack OPAL	SSDPE2KX040T8OP	984820
Intel® SSD DC P4610 Series (1.6TB, 2.5in PCIe 3.1 x4, 3D2, TLC) Generic Single Pack OPAL	SSDPE2KE016T8OS	984821
Intel® SSD DC P4610 Series (1.6TB, 2.5in PCIe 3.1 x4, 3D2, TLC) Generic 10 Pack OPAL	SSDPE2KE016T8OP	984822
Intel® SSD DC P4610 Series (3.2TB, 2.5in PCIe 3.1 x4, 3D2, TLC) Generic Single Pack OPAL	SSDPE2KE032T8OS	984823
Intel® SSD DC P4610 Series (3.2TB, 2.5in PCIe 3.1 x4, 3D2, TLC) Generic 10 Pack OPAL	SSDPE2KE032T8OP	984824

PCN Revision History:

Date of Revision:
August 6, 2019

Revision Number:
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Reason:
Originally Published PCN



Product Change Notification

117086 - 00

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